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APPLICATION NO. FILING DATE 09/989,263 11/19/2001		FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
		Michael A. Lamson	TI-31189	8850	
75	90 08/14/2002				
Gary C. Honeycutt			EXAMINER		
Godwin Gruber, P.C. Suite 655			MALDONADO, JULIO J		
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Richardson, TX	75081		ART UNIT	PAPER NUMBER	
			2823		
			DATE MAILED: 08/14/2002		

Please find below and/or attached an Office communication concerning this application or proceeding.

			Alexa N		111
	<i>₩</i> ,	Applica	ation No.	Applicant(s)	
	Offic Action Summary	09/989	<u></u>	LAMSON ET AL.	
	Ome Action Summary	Examir	ner	Art Unit	
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Period fo	The MAILING DATE of this communication or Reply	appears on	the cover sheet with the d	correspondence ac	ddress
- Exte after - If the - If NC - Failu - Any i	ORTENED STATUTORY PERIOD FOR RE MAILING DATE OF THIS COMMUNICATIO insions of time may be available under the provisions of 37 CFF SIX (6) MONTHS from the mailing date of this communication is period for reply specified above is less than thirty (30) days, a period for reply is specified above, the maximum statutory per tree to reply within the set or extended period for reply will, by start reply received by the Office later than three months after the material part of the part of the material part of the ma	R 1.136(a). In no reply within the strict will apply and	event, however, may a reply be tin tatutory minimum of thirty (30) day I will expire SIX (6) MONTHS from	nely filed s will be considered time the mailing date of this c	ly. ommunication.
1)[🛛	Responsive to communication(s) filed on 1	5 May 2002	)		
2a) <u></u>		This action			
3)	Since this application is in condition for allo				
, —	closed in accordance with the practice und on of Claims	ler <i>Ex parte</i>	Quayle, 1935 C.D. 11, 4	osecution as to th 53 O.G. 213.	e merits is
4) 🖂	Claim(s) 1-17 is/are pending in the applicat	ion.			
	4a) Of the above claim(s) <u>17</u> is/are withdraw	n from cons	ideration.		
	Claim(s) is/are allowed.				
6)⊠	Claim(s) <u>1-16</u> is/are rejected.			-	
	Claim(s) is/are objected to.				
8)[	Claim(s) are subject to restriction and	d/or election	requirement		
Application	on Papers				
9)∐ 7	The specification is objected to by the Exami	ner.			
10)∐ T	he drawing(s) filed on is/are: a)□ acc	cepted or b)[	objected to by the Exan	niner.	
	Applicant may not request that any objection to	the drawing(s	s) be held in abeyance. Se	e 37 CFR 1.85(a).	
11) 🗌 T	he proposed drawing correction filed on	is: a)[] :	approved b)⊡ disapprov	ed by the Examine	er.
	If approved, corrected drawings are required in	reply to this C	Office action.		
12)∐ T	he oath or declaration is objected to by the <b>i</b>	Examiner.			
Priority u	nder 35 U.S.C. §§ 119 and 120				
13) 🗌 📝	Acknowledgment is made of a claim for forei	gn priority u	nder 35 U.S.C. § 119(a)	-(d) or (f).	
a)[	All b) Some * c) None of:				
•	1. Certified copies of the priority docume	nts have be	en received.		
2	2. Certified copies of the priority docume	nts have bee	en received in Application	n No	
	B. Copies of the certified copies of the pri application from the International E se the attached detailed Office action for a lis	ority docum	ents have been received Rule 17.2(a))	in this National S	Stage
	knowledgment is made of a claim for domes				ammilia = #1
	☐ The translation of the foreign language p				application).
15) 🗌 Ad	cknowledgment is made of a claim for domes	stic priority u	inder 35 U.S.C. 88 120 a	veu. and/or 121	
ttachment(s					
) 🔲 Notice	of References Cited (PTO-892) of Draftsperson's Patent Drawing Review (PTO-948) ation Disclosure Statement(s) (PTO-1449) Paper No(s)	·	4) Interview Summary (I 5) Notice of Informal Pa 6) Other:	PTO-413) Paper No(s tent Application (PTO	152)
Patent and Trad O-326 (Rev.	0.4.00	Action Summa	rv	Port of f	Papar No. 4

Art Unit: 2823

#### **DETAILED ACTION**

Page 2

### Claim Objections

1. Claims 11 and 14 are objected to because of the following informalities: in claim 11, where applicants cite "...said device is packages as a..." should cite "...said device is packaged as a..."; and in claim 14, where applicants cite "...shell comprises ceramic..." should cite "...shell comprises a ceramic...". Appropriate correction is required.

# Claim Rejections - 35 USC § 102

2. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

- (e) the invention was described in-
- (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effect under this subsection of a national application published under section 122(b) only if the international application designating the United States was published under Article 21(2)(a) of such treaty in the English language; or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that a patent shall not be deemed filed in the United
- invention by the applicant for patent, except that a patent shall not be deemed filed in the United States for the purposes of this subsection based on the filing of an international application filed under the treaty defined in section 351(a).
- 3. Claims 1, 3 and 10-12 are rejected under 35 U.S.C. 102(e) as being anticipated by Choi (U.S. 6,013,109).

In reference to claims 1, and 12, Choi (Figs.3A-3D) teach a crack-resistance semiconductor package including a plurality of wire bonds (24) connecting pads on an integrated circuit chip (23) to conductive leads (25) of a semiconductor package; a low dielectric constant sheath (26) surrounding each wire (24); and a mold compound (29)

Application/Control Number: 09/989,263

Art Unit: 2823

encasing the chip (23), sheathed wires, and leads (25) (column 2, line 66 – column 3, line 45).

In reference to claims 3, 10 and 11, Choi teaches that the thickness of the dielectric sheath is 2.5 microns minimum in each surface (column 3, lines 25-27); that the device is packaged in a ball grid array package; and that the device is packaged as a leaded surface mount package (column 2, line 66 – column 3, line 45).

# Claim Rejections - 35 USC § 103

- 4. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
  - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 5. Claims 2, 4-9 and 16 are rejected under 35 U.S.C. 103(a) as being unpatentable over Choi ('109) in view of Eysermans (U.S. 4,048,670).

In reference to claims 2, 8, 9, 13 and 16, Choi substantially teach all aspects of the invention but fails to show that the dielectric sheath comprises a foamed thermoplastic polymer consisting of polyurethane. However, Eysermans in a related art to stress-free package teach using foamed polyurethane as a resilient material (column 4, lines 13-39). Therefore, it would have been obvious to one of ordinary skill in the art at the time of the invention was made to use foamed polyurethane as taught by Eysermans to surround the bonding wires of the package device of Choi, since polyurethane is a material that can withstand shock (i.e. resilient), and can provide physical support against differential forces (column 4, lines 13-39).

Application/Control Number: 09/989,263

Art Unit: 2823

In reference to claim 4, Choi in combination with Eysermans teach using foamed polyurethane as a dielectric sheath, but fails to expressly teach that the dielectric constant of the sheath surrounding bond wires is in the range of 1.0 to 2.3. However, since the material used as the dielectric sheath is the same as that of the claimed invention, it is inherently known that the dielectric constant of the sheath is in the range of 1.0 to 2.3.

In reference to claims 5, 6 and 7, Choi in combination with Eysermans substantially teach all aspects of the invention but fails to show that the distance between wires is in the range of 50 to 100 microns; the mutual capacitance between bond wires is lower by a factor of 3; and the dielectric constant of the molding compound is in the range of 3.8 to 4.2. However, the selection of the claimed ranges is obvious because it is a matter of determining optimum process condition by routine experimentation with a limited number of species. In re Jones, 162 USPQ 224 (CCPA 1955)(the selection of optimum ranges within prior art general conditions is obvious) and In re Boesch, 205 USPQ 215 (CCPA 1980)(discovery of optimum value of result effective variable in a known process is obvious).

6. Claims 14 and 15 are rejected under 35 U.S.C. 103(a) as being unpatentable over Choi ('109) in view of Featherby et al. (U.S 6,368,899).

Choi substantially teaches all aspects of the invention but fails to teach that the cavity package shell comprises a ceramic or a composite polymer. However, Featherby et al. (Fig.8) teach a package device in which a cavity package shell comprises a ceramic material (column 1, lines 8-35) or a composite polymer (12/300/400) (column

Art Unit: 2823

11, line 50 – column 12, line 29). Therefore, it would have been obvious to one of ordinary skill in the art at the time of the invention was made to use a ceramic cavity package shell as taught by Featherby et al. in the package device of Choi, since ceramic cavity packages are well-known materials used to prevent impurities from entering critical portions of the package (column 1, lines 23-27). It would also have been obvious to one of ordinary skill in the art to form a composite polymer cavity package shell as taught by Featherby et al. in the package device of Choi, since this would result in a hermetic package (column 3, lines 12-14).

#### Conclusion

7. Papers related to this application may be submitted directly to Art Unit 2823 by facsimile transmission. Papers should be faxed to Art Unit 2823 via the Art Unit 2823 Fax Center located in Crystal Plaza 4, room 3C23. The faxing of such papers must conform to the notice published in the Official Gazette, 1096 OG 30 (15 November 1989). The Art Unit 2823 Fax Center number is (703) 305-3432. The Art Unit 2823 Fax Center is to be used only for papers related to Art Unit 2823 applications.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to **Julio J. Maldonado** at **(703)** 306-0098 and between the hours of 8:00 AM to 4:00 PM (Eastern Standard Time) Monday through Friday or by e-mail via <u>julio.maldonado@uspto.gov</u>. If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Wael Fahmy, can be reached on (703) 308-4918.

Application/Control Number: 09/989,263

Art Unit: 2823

Page 6

Any inquiry of a general nature or relating to the status of this application should be directed to the **Group 2800 Receptionist** at **(703) 308-0956**.

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